

Lecture 15 - Digital Circuits: Inverter Basics - Outline

- **Announcements**

 - Handout - Lecture Outline and Summary

 - The MOSFET alpha factor - use definition in lecture, not text

 - ["+1" is missing in Eq. 10.23]

- **Review - Linear equivalent circuits**

 - Notation: $i_D = I_D + i_d(t)$ where i_D = total current; I_D = bias; $i_d(t)$ = increment

 - LECs: the same for npn and pnp; the same for n-MOS and p-MOS;

 - all parameters depend on bias, so maintaining a stable bias is critical

- **Digital building blocks - inverters**

 - A generic inverter

 - MOS inverter options

- **Digital inverter performance metrics**

 - Transfer characteristic: logic levels and noise margins

 - Power dissipation

 - Switching speed

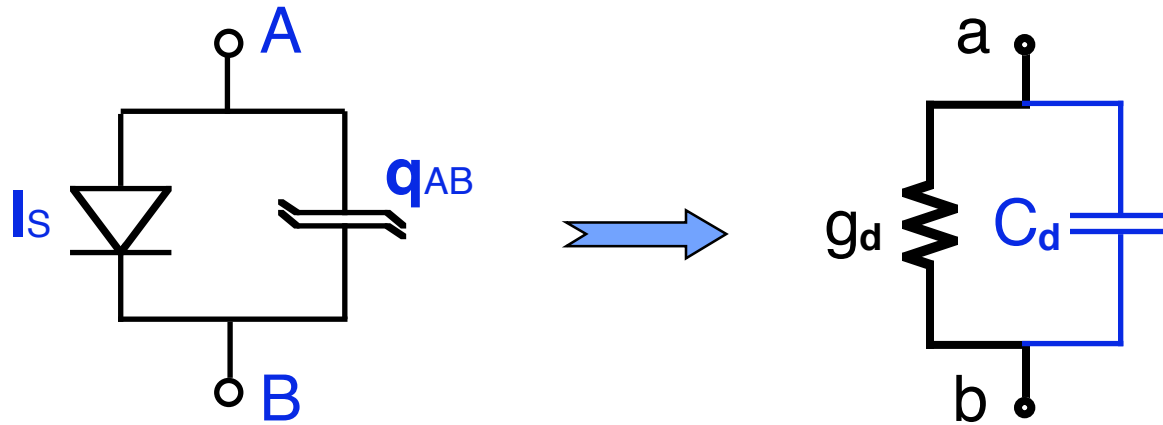
 - Fan-out, fan-in

 - Manufacturability

- **Comparing the MOS options**

 - And the winner is....

- **LEC for the p-n junction diode:**



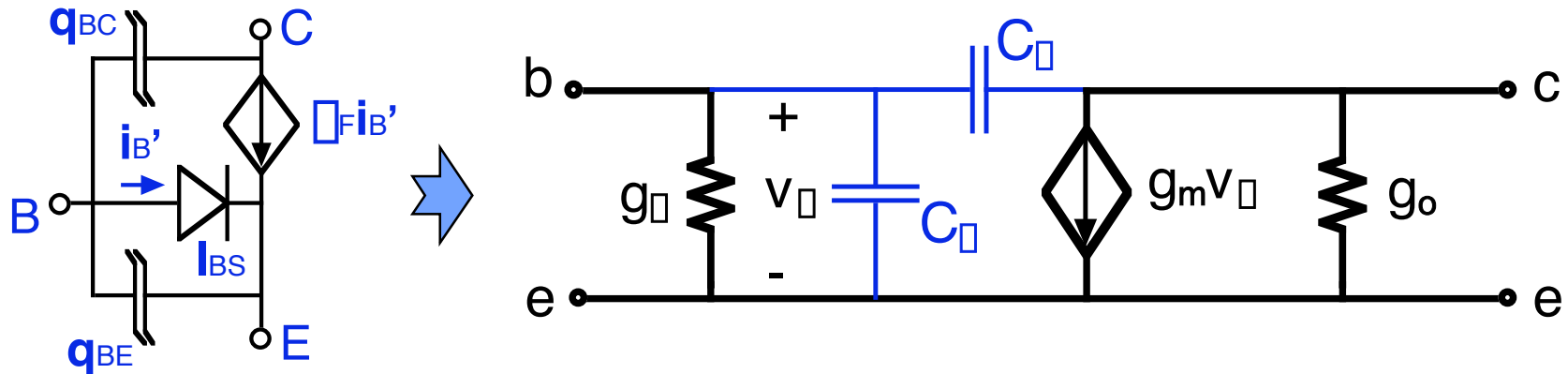
$$g_d = \frac{q}{kT} I_{BS} e^{qV_{AB}/kT} \quad \square \quad \frac{qI_D}{kT}$$

$$C_d = C_{dp} + C_{df}, \text{ where } C_{dp}(V_{AB}) = A \sqrt{\frac{q \epsilon_{Si} N_{Ap}}{2(\epsilon_b \epsilon V_{AB})}} \quad \text{and}$$

$$C_{df}(V_{AB}) = \frac{qI_D}{kT} \frac{[w_p \epsilon x_p]^2}{2D_e} = g_d \epsilon_d \quad \text{with } \epsilon_d \equiv \frac{[w_p \epsilon x_p]^2}{2D_e}$$

(Note: The capacitance expressions assume an n⁺-p diode)

• **Linear equivalent circuit for the BJT in F.A.R:**



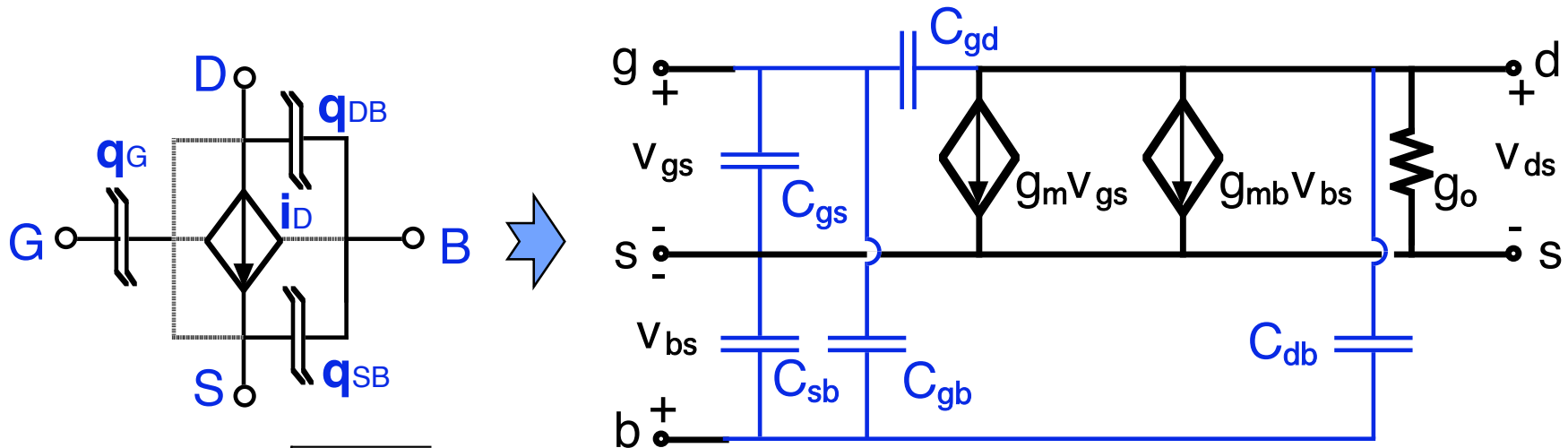
$$g_m \approx \frac{q|I_C|}{kT} \qquad g_{\pi} = \frac{g_m}{\beta_o}$$

$$g_o \approx \beta_o |I_C| \quad \text{or} \quad \left| \frac{I_C}{V_A} \right|$$

$$C_{\mu} = g_m \tau_b + \text{B-E depletion capacitance, where } \tau_b = \frac{w_B^2}{2D_{\text{minority in base}}}$$

$$C_{\pi} = \text{B-C depletion capacitance}$$

• **Linear equivalent circuit for the MOSFET in saturation:**



$$g_m \approx \sqrt{2K |I_D|}$$

$$g_o \approx \frac{I_D}{V_A} \quad \text{or} \quad \frac{I_D}{V_A}$$

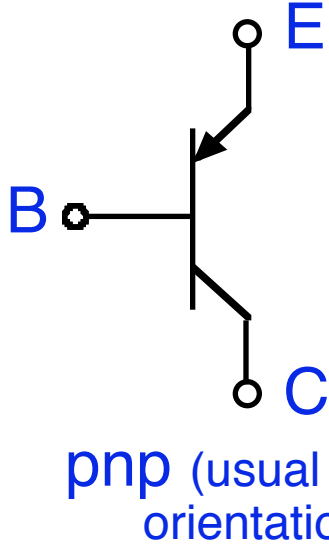
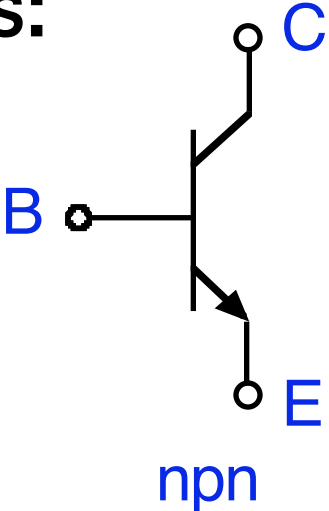
$$g_{mb} = \beta g_m = \beta \sqrt{2K |I_D|} \quad \text{with} \quad \beta = \frac{1}{C_{ox}^*} \sqrt{\frac{\epsilon_{Si} q N_A}{q \epsilon_p |V_{BS}|}}$$

$$C_{gs} = \frac{2}{3} W L C_{ox}^* \quad C_{sb}, C_{gb}, C_{db} : \text{depletion region capacitances}$$

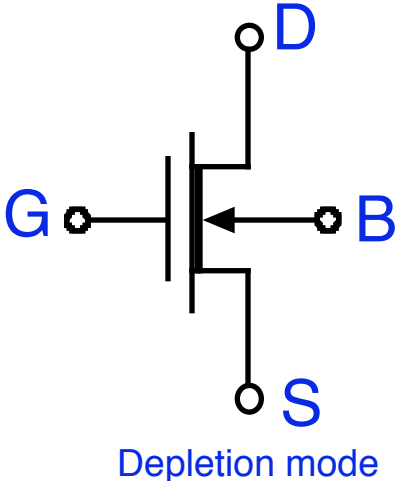
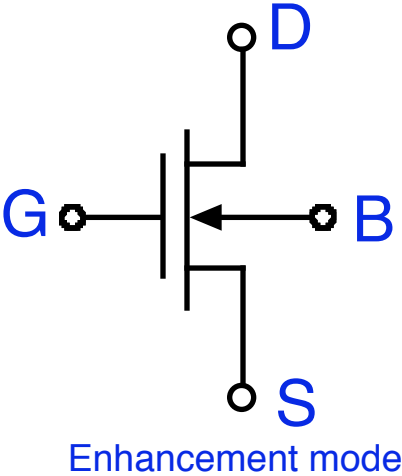
$$C_{gd} = W C_{gd}^* \quad \text{where } C_{gd}^* \text{ is the gate-to-drain fringing and overlap capacitance per unit gate width}$$

Circuit symbols:

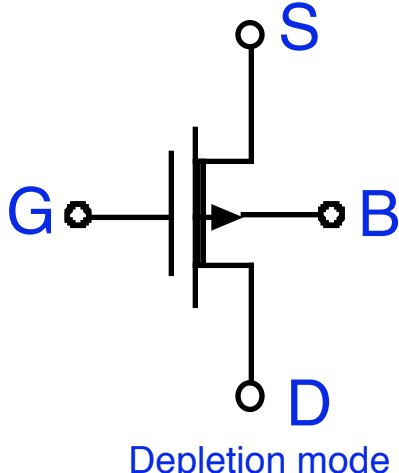
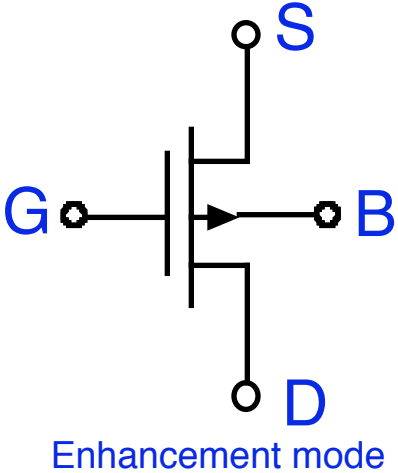
BJT:



MOSFET:



n-channel

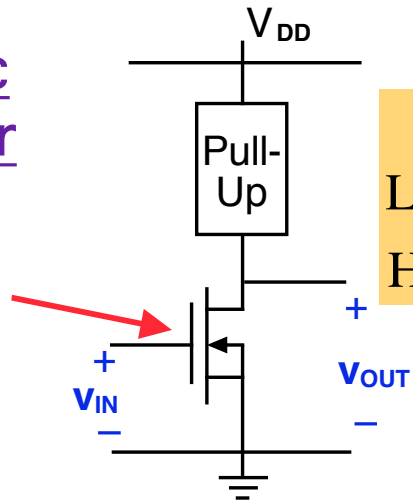


p-channel (usual circuit orientation)

• **Building Blocks for Digital Circuits: inverters**

A basic inverter

Switch:
on or off



v_{IN}	v_{OUT}
Lo (0)	Hi (1)
Hi (1)	Lo (0)

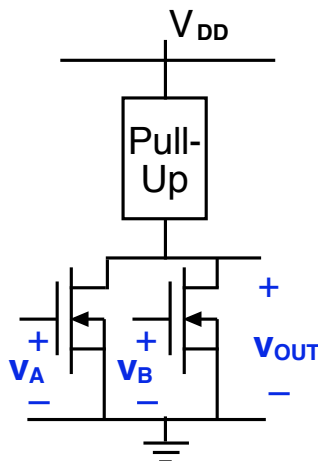
Performance metrics

- Transfer characteristic
- Logic levels
- Noise margins
- Power dissipation
- Switching speed
- Fan-in/Fan-out
- Manufacturability

Logic gates

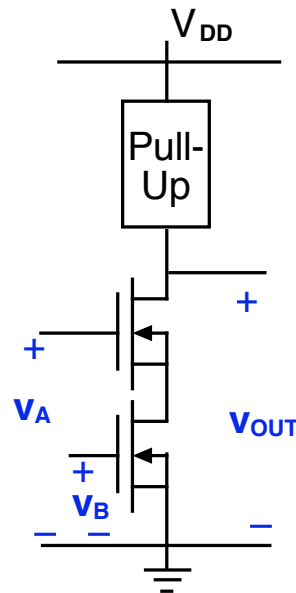
NOR:

v_A	v_B	v_{OUT}
0	0	1
0	1	0
1	0	0
1	1	0

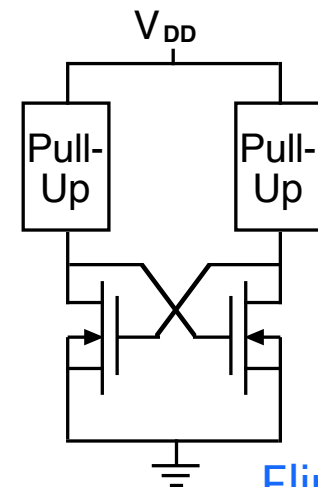


NAND:

v_A	v_B	v_{OUT}
0	0	1
0	1	1
1	0	1
1	1	0



Memory cell



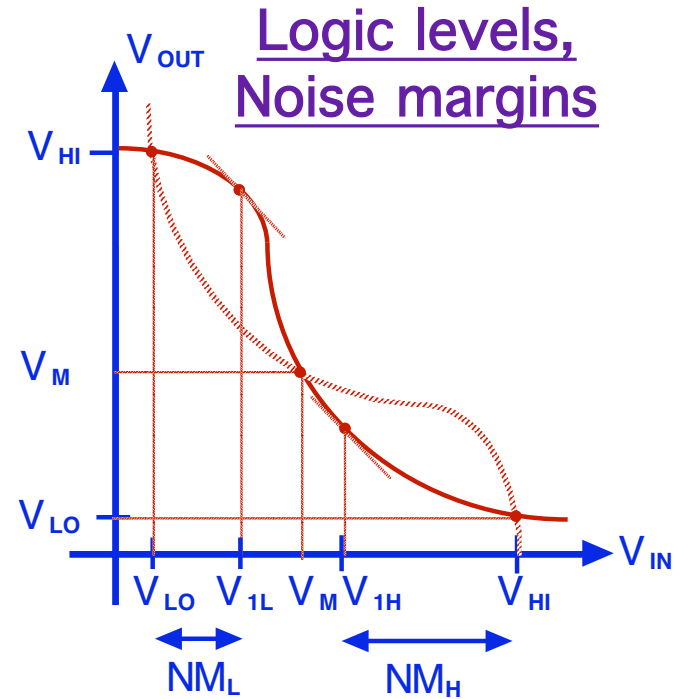
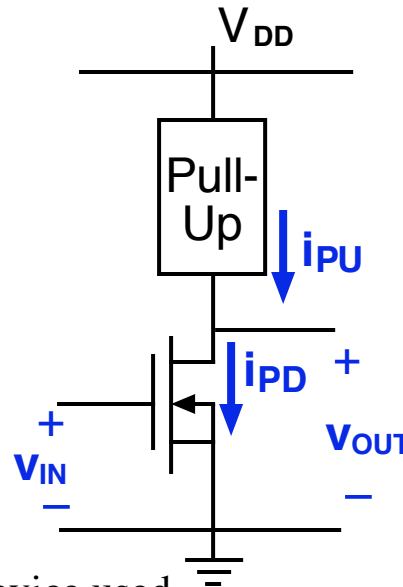
Flip-flop

Transfer characteristic

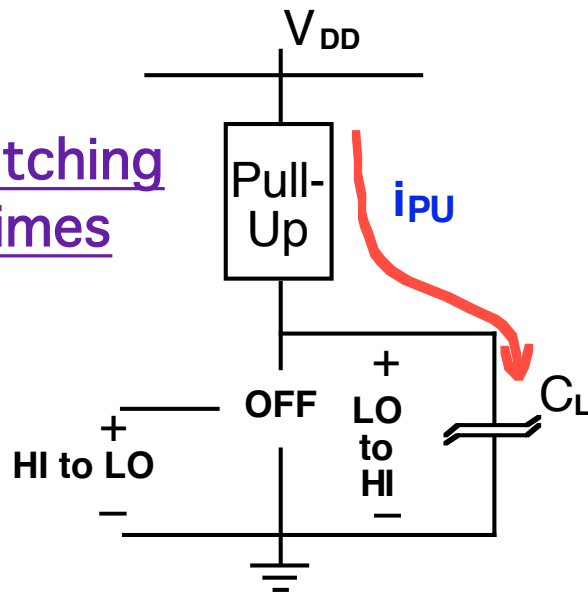
Node equation: $i_{PD} = i_{PU}$

$$i_{PD} = \begin{cases} 0 & \text{when } v_{IN} < V_{T,PD} \\ K_{PD} (v_{IN} - V_{T,PD})^2 / 2 & \text{when } 0 < [v_{IN} - V_{T,PD}] < v_{OUT} \\ K_{PD} (v_{IN} - V_{T,PD} - v_{OUT} / 2) v_{OUT} & \text{when } 0 < v_{OUT} < [v_{IN} - V_{T,PD}] \end{cases}$$

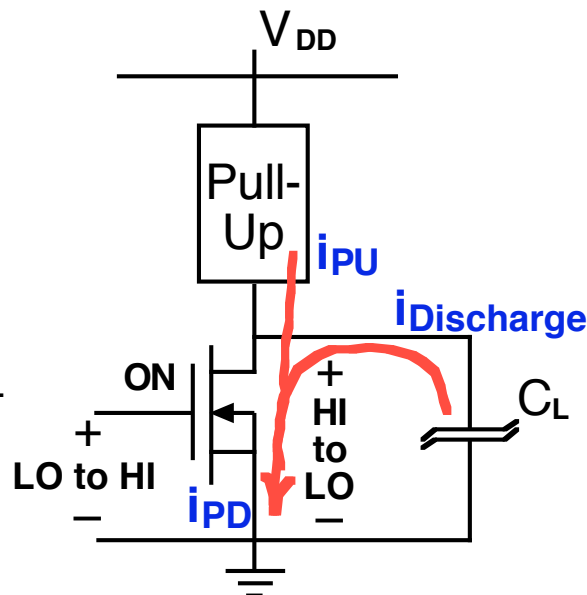
i_{PU} : Depends on the specific pull-up device used.



Switching times



Charging cycle: $i_{Charge} = i_{PU}$



Discharging cycle: $i_{Discharge} = i_{PD} - i_{PU}$

Power

$$P_{Total} = P_{Static} + P_{Dynamic}$$

Static:

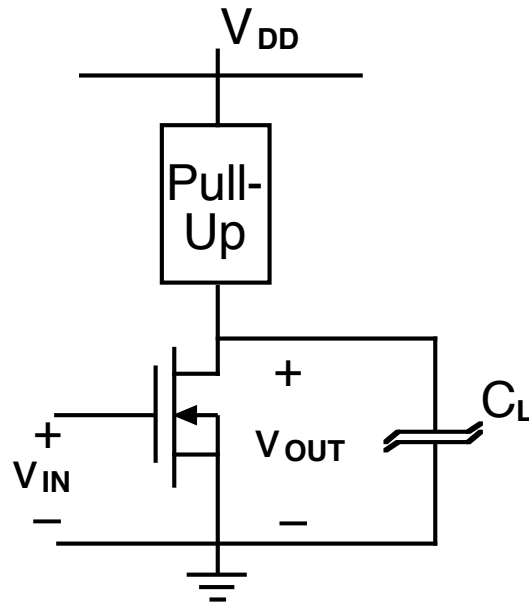
$$P_{Static} = \frac{1}{2} i_{PU,on} V_{DD}$$

Dynamic:

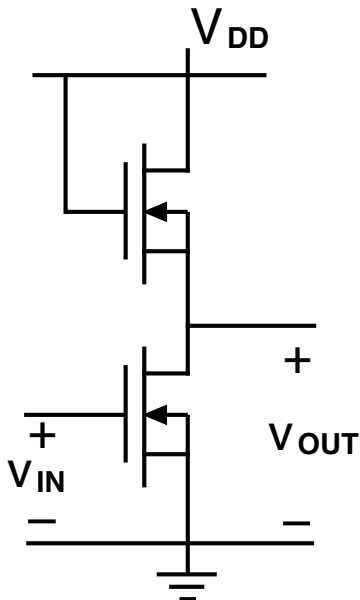
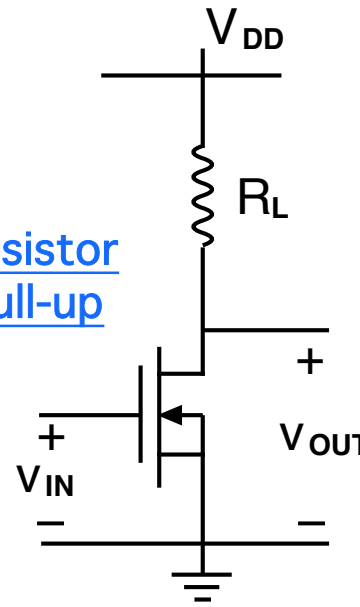
$$P_{Dynamic} = C_L V_{DD}^2 \cdot f$$

MOS inverters

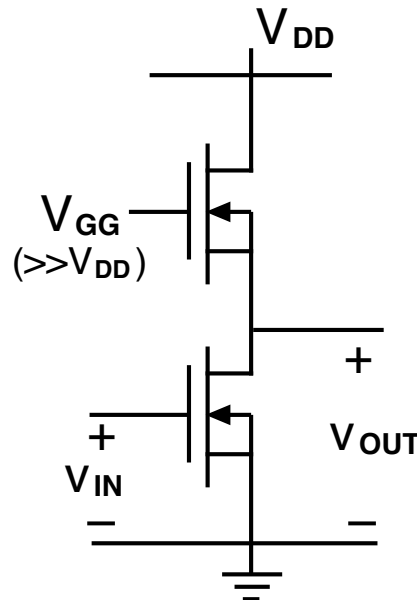
Generic
inverter



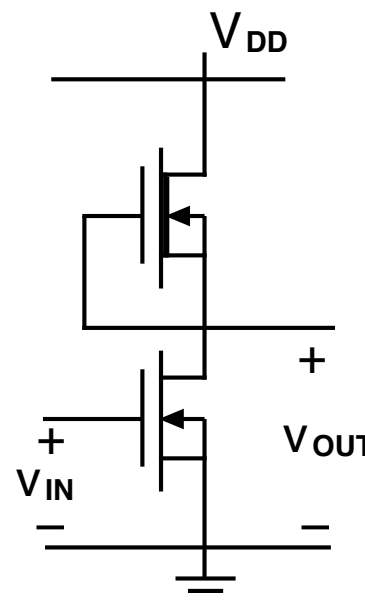
Resistor
pull-up



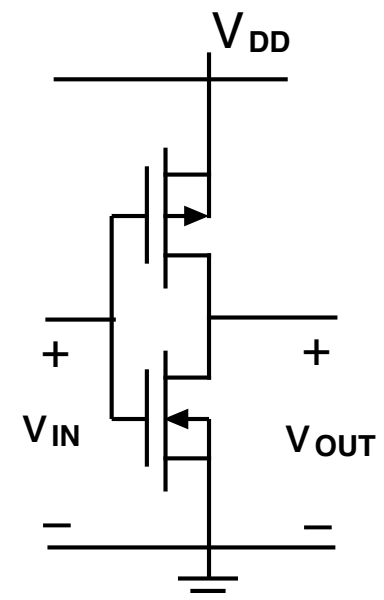
n-channel, e-mode pull-up
 V_{DD} on gate



V_{GG} on gate

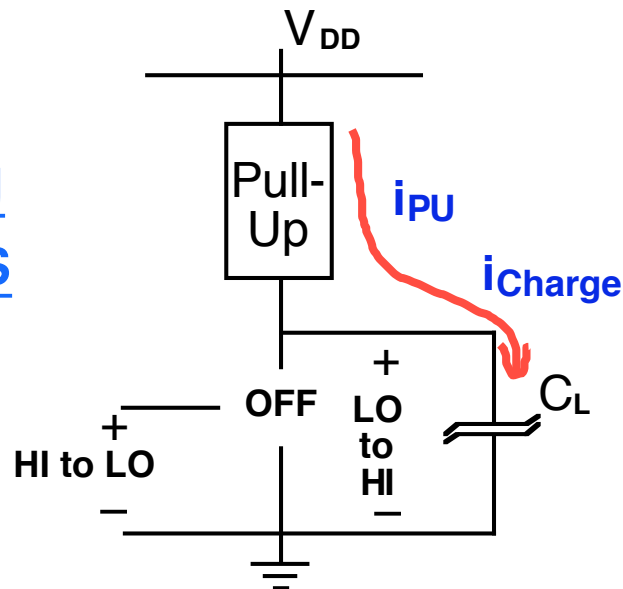


n-channel, d-mode pull-up

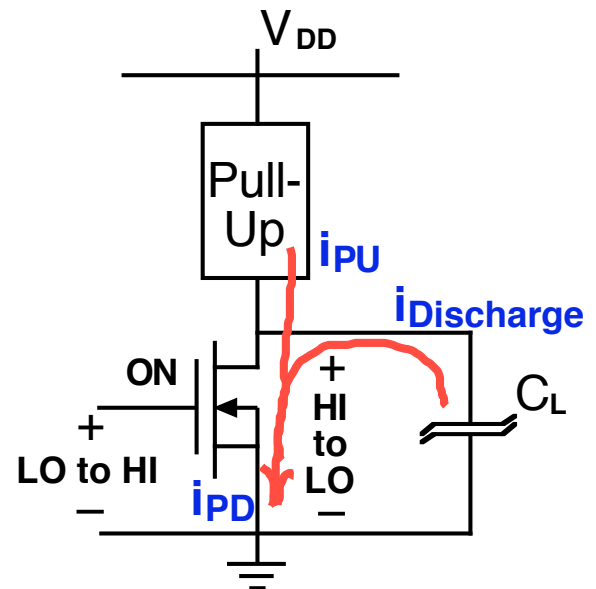


p-channel, e-mode pull-up (CMOS)

Switching transients

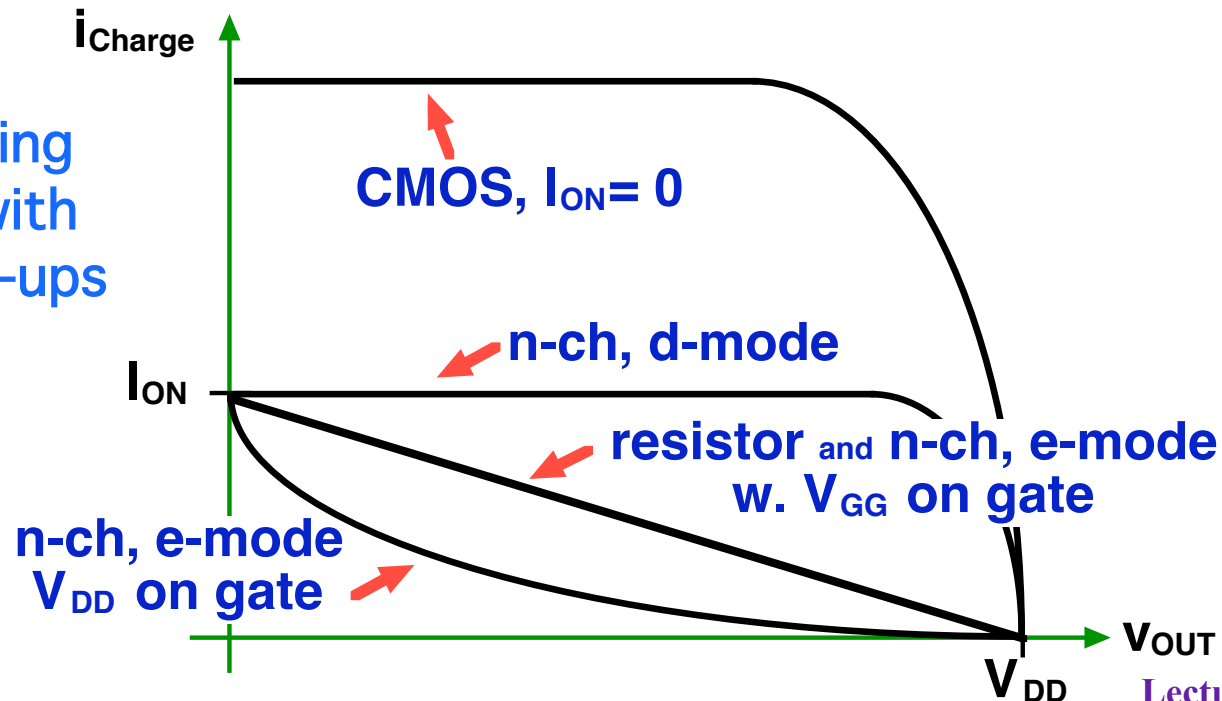


Charging cycle: $i_{\text{Charge}} = i_{\text{PU}}$



Discharging cycle: $i_{\text{Discharge}} = i_{\text{PD}} - i_{\text{PU}}$

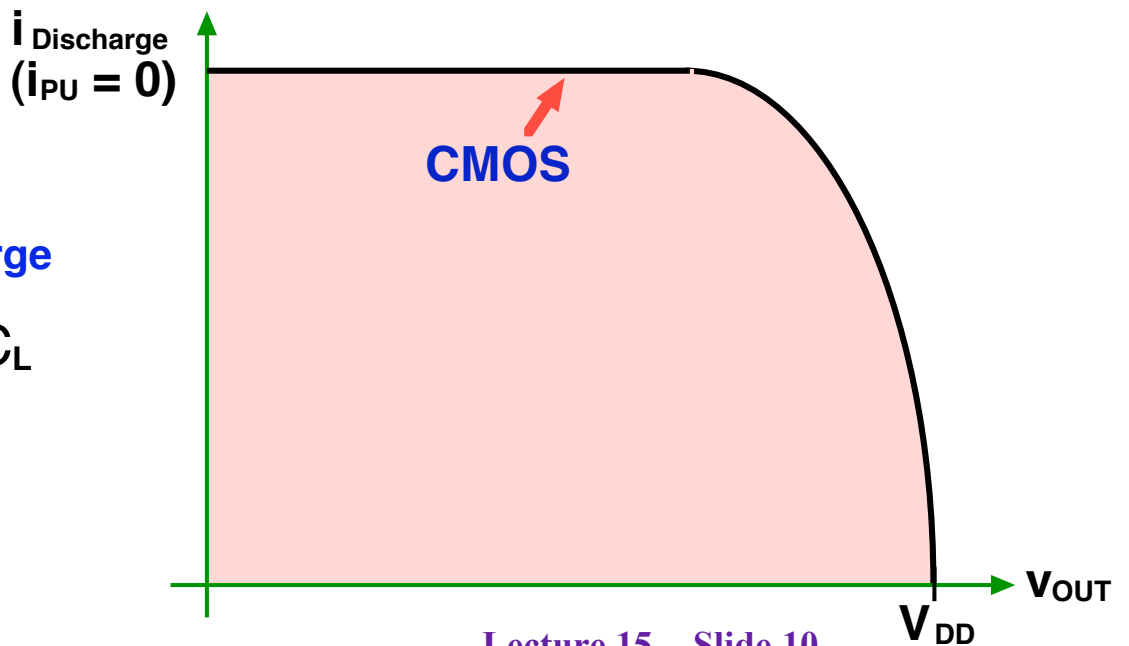
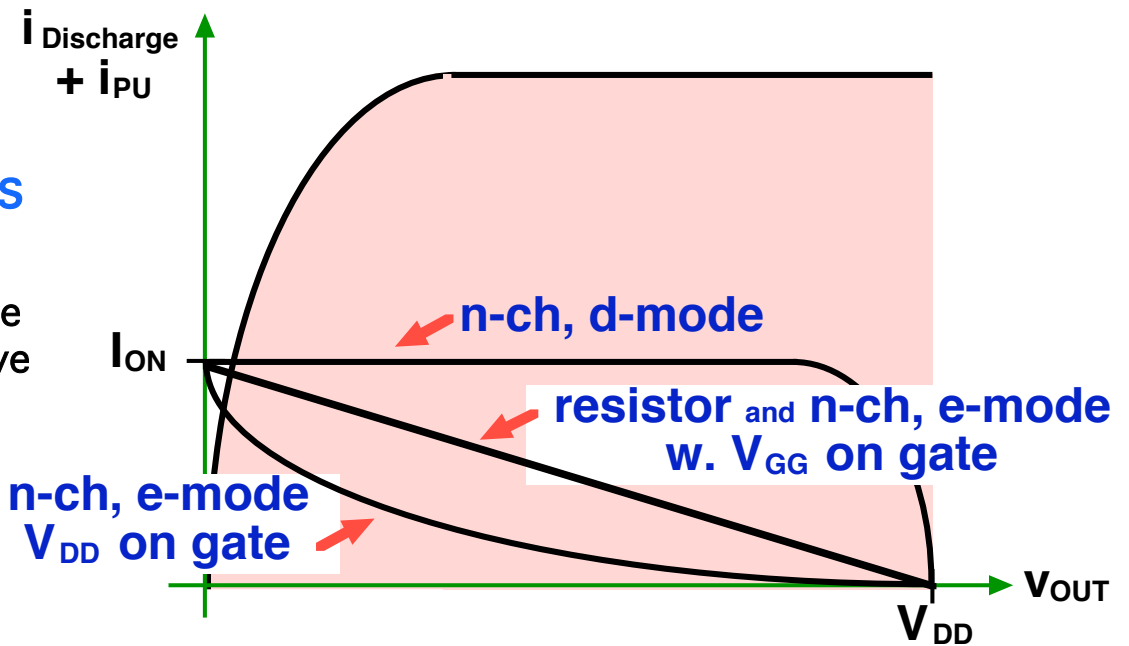
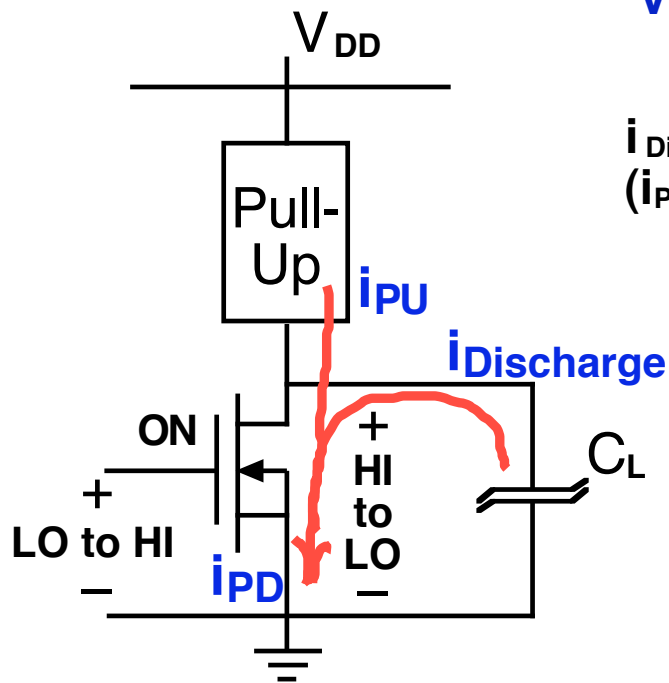
The charging currents with various pull-ups



Switching transients

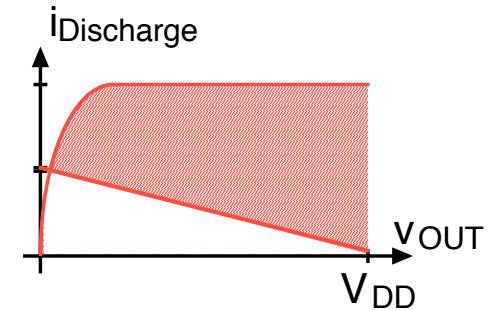
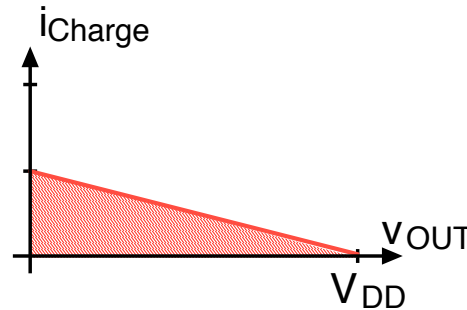
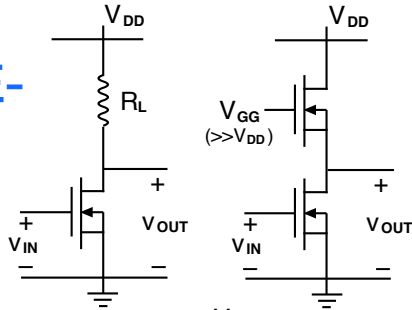
The discharging currents with various pull-ups

Note: The discharge current is the difference between the upper curve and the appropriate lower curve.

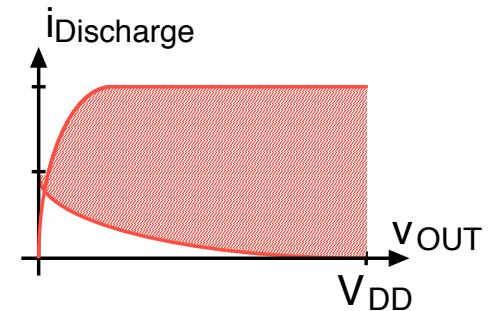
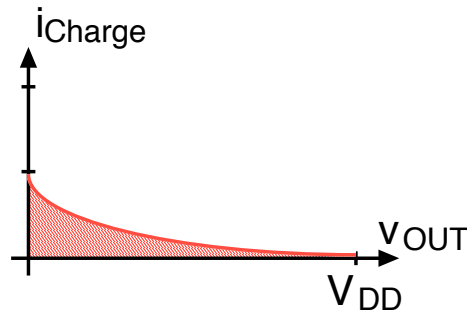
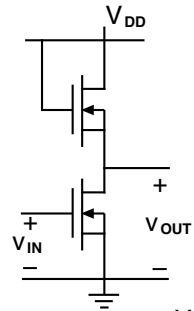


Switching transients: summary of charge/discharge currents

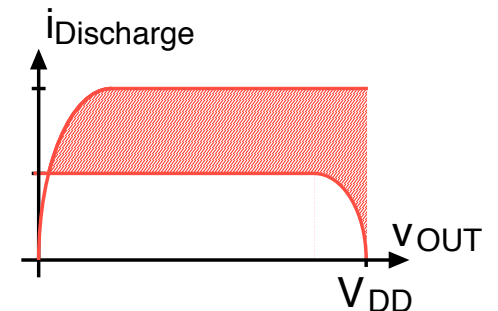
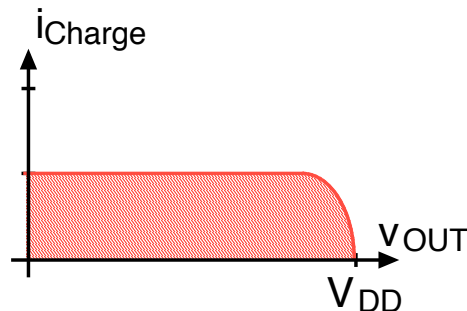
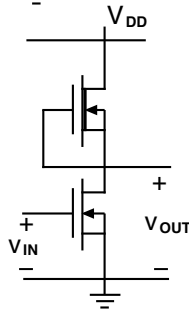
Resistor and E-mode pull-up
(V_{GG} on gate)



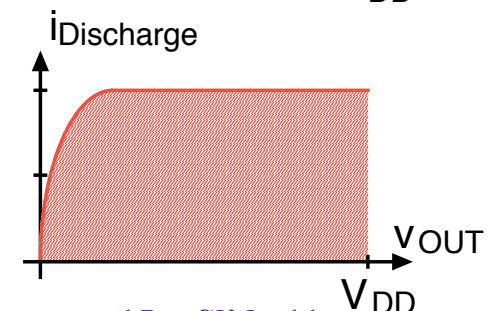
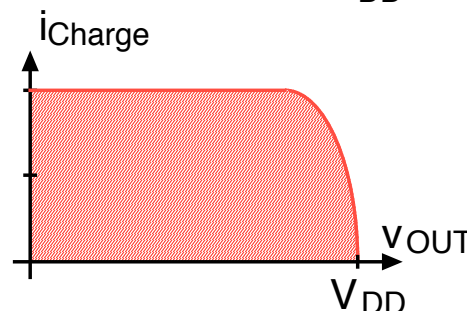
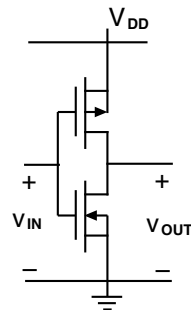
E-mode pull-up
(V_{DD} on gate)



D-mode pull-up
(called "n-MOS")



CMOS



Lecture 15 - Digital Circuits: Inverter Basics - Summary

- **Digital building blocks - inverters**

A generic inverter - Switch = pull-down device, Load = pull-up device

MOS inverter options - Pull-down: n-channel, e-mode (faster than p-channel)

Pull-up: 1. resistor; 2. n-channel, e-mode w. and w.o. gate bias;
3. n-channel, d-mode; 4. p-channel, e-mode (CMOS)

- **Digital inverter performance metrics**

Transfer characteristic

Logic levels: V_{HI} , V_{LO}

Noise margins: NM_{HI} (high), and NM_{LO} (low)

Design variables: choice of pull-up device
pull-up and pull-down thresholds
device sizes (absolute and relative)

Power dissipation: stand-by power and switching dissipation

Switching speed: capacitive load
charge and discharge currents critical

Fan-out, fan-in: minimal issue in MOS; more so with BJT logic

Manufacturability: small, fast, low-power, reliable, and cheap

- **Comparing the MOS options**

And the winner is....CMOS